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Challenges in the practical application of LCA exemplified by DTAG

Herausforderungen in der praktischen Anwendung von LCA am Beispiel der DTAG

Steffen Wasmus, Deutsche Telekom AG Berlin, September 2023



### Our sustainability commitments are relevant for product design



We take responsibility for climate and resource protection and support the 1.5-degree target of the Paris climate agreement<sup>1)</sup> Net-zero for internal emissions until 2025

100 % renewable electricity for DT Group from 2021 onwards

## 55 % reduction

Scope 1-3 emissions by 2030

### Net-zero

From the production to the customer until 2040

Save resources:

### Sustainable packaging

100% for all new T-branded devices in 2022 100% for all devices in 2025

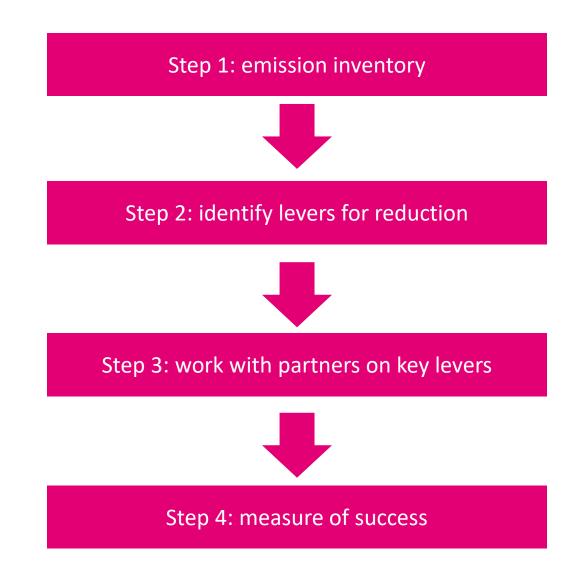
### **Full circularity**

around technology and devices until 2030

## How to approach the target achievement?



The mobile phone business constitutes a substantial portion of DTAG's scope 3 emissions and needs to contribute to reductions



Key consideration • What is the current basis of emissions that needs to be reduced? Need Accurate emission data for each device type in portfolio • Data need to be provided by partners in the supply chain

Challenges

- Not every partner has the data as of now
- Lack of comparability of data from different sources
- What is the "calibration factor" to make data comparable?
- What is the reference factor (unit/device)?

### THE ECO RATING METHODOLOGY – the solution to the challenges The tool

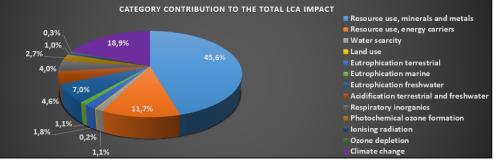
#### EXCEL-BASED QUESTIONNAIRES ALLOWING TO OBTAIN THE FULL EVALUATION OF THE DEVICE

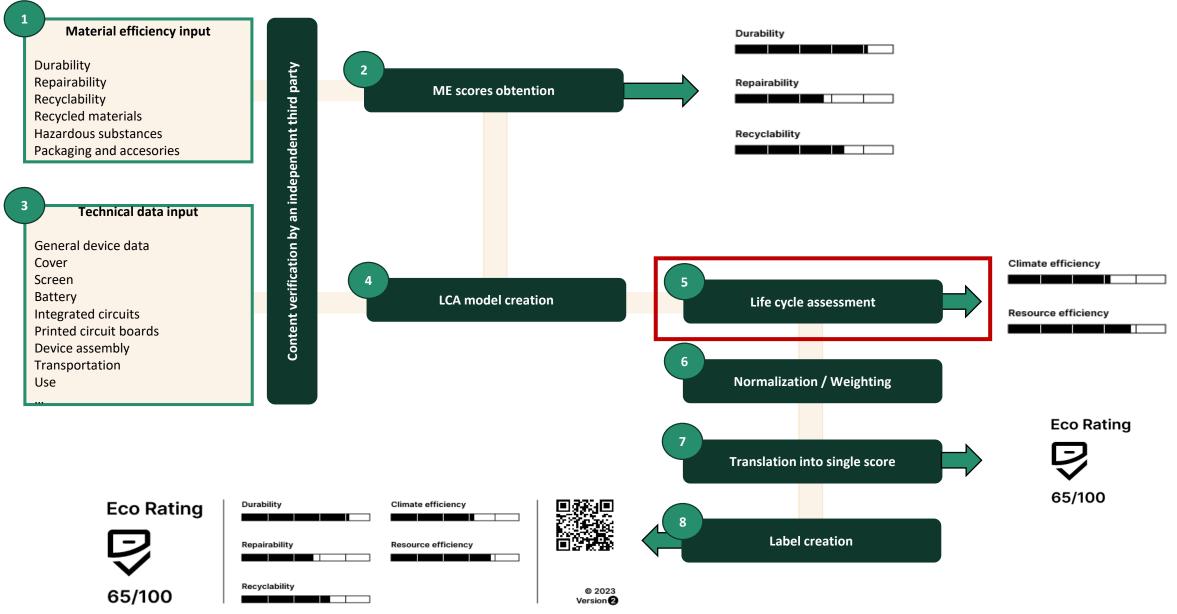


Deutsche Telekom, Orange, Telefónica, Telia and Vodafone ("the Consortium o public communication, including making available, of all or part of this of a statement of the stat											
BASIC DEVICE PARAMETERS					_					DURABILIT	
Vendor name	Free text									DURABILIT	ĩ
Device model name	Free text		Deutsche Telekom, Orange, Teletónica, Telia and Vodatone ("the Consortium members") are for now the owners of the methodology. Reproduction, distribution, transformation and put								
Device ID code (vendor code used to identify this device)	Free text									members,	is prohibited.
Release date	Date								SCORES		
Device type	Select		REF	Fill in the score for the product	Product	Factor	1	2			
Device height	mm		Rer	Pill in the score for the product	Product	racior		4	, °	•	
Device width	mm		DUR-01	Guarantee period for the terminal and its components		15%	1 year		2 years		more than 2 years
Device thickness	mm										
Internal storage capacity	GB										
RAM memory	GB										
Total weight of the device	grams										
Weight of the charger, including cable	grams		DUR-02	Dust protection		10%	P4x		IP5x		IP6x
Weight of other accesories included in the packaging	grams		004-02								
COVER MANUFACTURING			DUR-03	Water Protection		10%	Px3	Px4	IPx5	Px6	IP 2 IPx7
Weight of aluminum in the casing	grams										
Weight of steel in the casing	grams		DUR-04	Drop resistance		25%	45 ≤ x < 75 cm	75 ≤ x < 100 cm	100 ≤ x < 120 cm	120 ≤ x < 150 cm	x ≥ 150 cm
Weight of PC in the casing	grams			propriorite				10-11-10-0			
Weight of ABS in the casing	grams										
Weight of glass in the casing	grams						1		1	1	
SCREEN MANUFACTURING											
Screen area	cm2		DUR-05	Battery life (full charge cycles)		25%	400 ≤ x < 600 cycles	600 ≤ x < 800 cycles	800 s x < 1000 cycles	1000 ≤ x < 1200 cycles	x ≥ 1200 cycles
Screen technology	Select										
Screen recimology	Delect							1			
BATTERY MANUFACTURING											
Weight of the battery pack	grams			Charge Connector lifetime (number of times without		15%	10,000 ≤ x < 20,000 times		20,000 ± x < 30,000 times		x ≥ 30,000 times
Capacity of the battery	mAh		DUR-05								
Battery voltage	V		DUR-06	damage)							
INTEGRATED CIRCUITS MANUFACTURING					Incomplete	100%					
Area of silicon die size in all the integrated circuits with more than 12 pins/balls	cm2			Max	5						
Area of silicon die size in RAM memory integrated circuits	cm2										
Area of silicon die size in internal storage memory integrated circuits	cm2									DELIGABILITY	
Total number of integrated circuits with more than 12 pins/balls in the device	#								REPARABILITY	, REUSABILITY	& UPGRADAB
									SCORES		
PRINTED CIRCUIT BOARD MANUFAC	TURING		REF	Fill in the score for the product	Product	Factor	1	2	3 3 SCORES	4	
Area of main PCB	cm2			Period of time of regular updated support of operating systems and firmware							
Type of PCB (Main PCB)	Select		REP-01			15%	1 year	2 years	3 years	4 years	5 years
Number of copper layers of main PCB	Select			Period of time of available spare parts and components		15%	1 year	2 years	3 years	4 years	5 years
Area of PCB 2	cm2		REP-02	(available on-line, at reasonable price and delivered in							
Type of PCB (PCB 2)	Select			a maximum of 15 days)							
Number of copper layers of PCB 2	Select			Information to the user on how to proceed and the		5%	In the manufacturer web- page or user-guide or In- box paper		In the manufacturer web-		In the manufacturer web- page and user-guide
Area of PCB 3	cm2		REP-03	tools to use to a secure data deletion of all user data					page and user-guide or		
Type of PCB (PCB 3)	Select			without compromising the functionality of the device					h-box paper	ar	and in-box paper

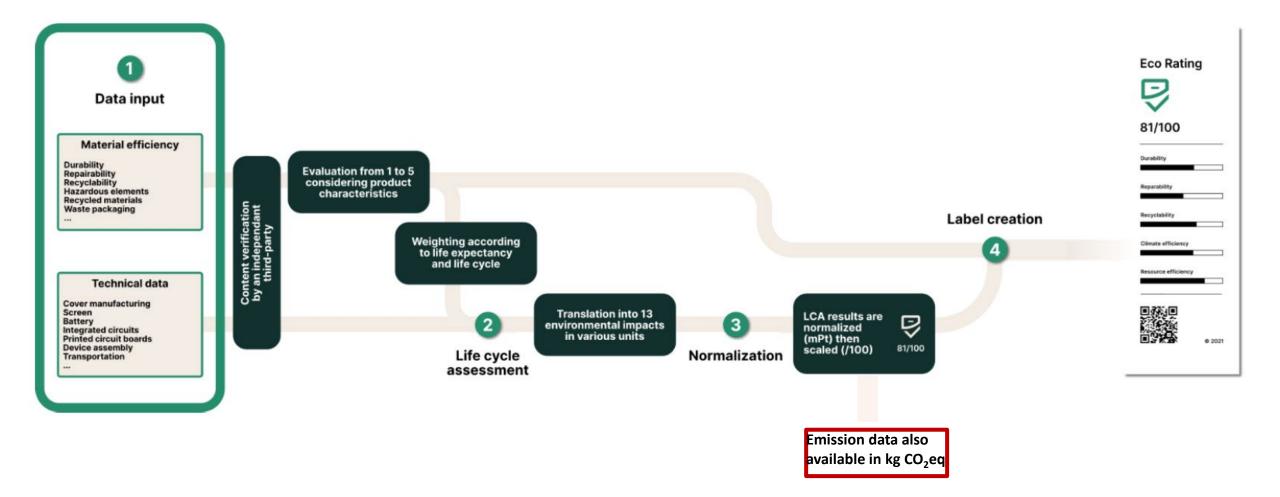
LIFE CYCLE ASSESSMENT

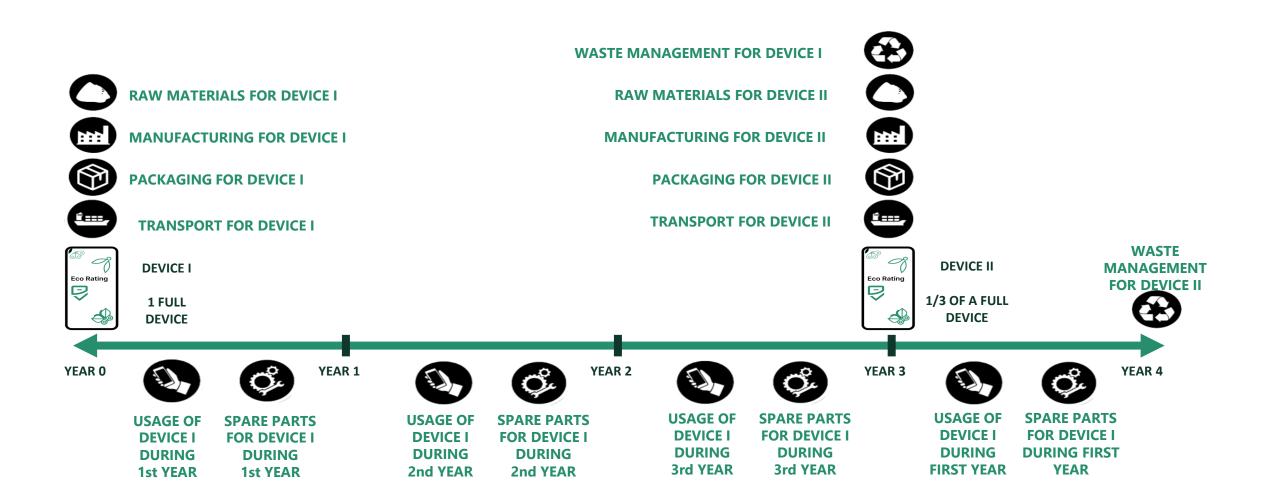
OVERALL RESULT	SCORE	MATERIAL EFFICIENCY ASSESSMENT							
ECO-RATING SCORE	80	DURABILITY							
MATERIAL EFFICIENCY RESULTS	SCORE	WASTE PACKAGING AND ACCESORIES UPGRADE ABILITY							
DURABILITY	58								
REPAIRABILITY / REUSABILITY / UPGRADEABILITY	43	RECYCLED MATERIALS CONTENT							
RECICLABILITY AND RECOVERABILITY	62	USE OF HAZARDOUS & RESTRICTED SUBSTANCES							
USE OF HAZARDOUS & RESTRICTED SUBSTANCES	100	LIFE CYCLE ASSESSMENT 7,5%							
RECYCLED MATERIALS CONTENT	88								
WASTE PACKAGING AND ACCESORIES	40	16,6% 3,4% 72,5% RAW MATERIALS AND MANUFACTURING STAGE TRANSPORT STAGE USE & REINVESTMENT STAGE USE & REINVESTMENT STAGE							
ADDTIONAL RESULTS	SCORE								
LOW CLIMATE CHANGE	68								
LOW RESOURCE USE	83								

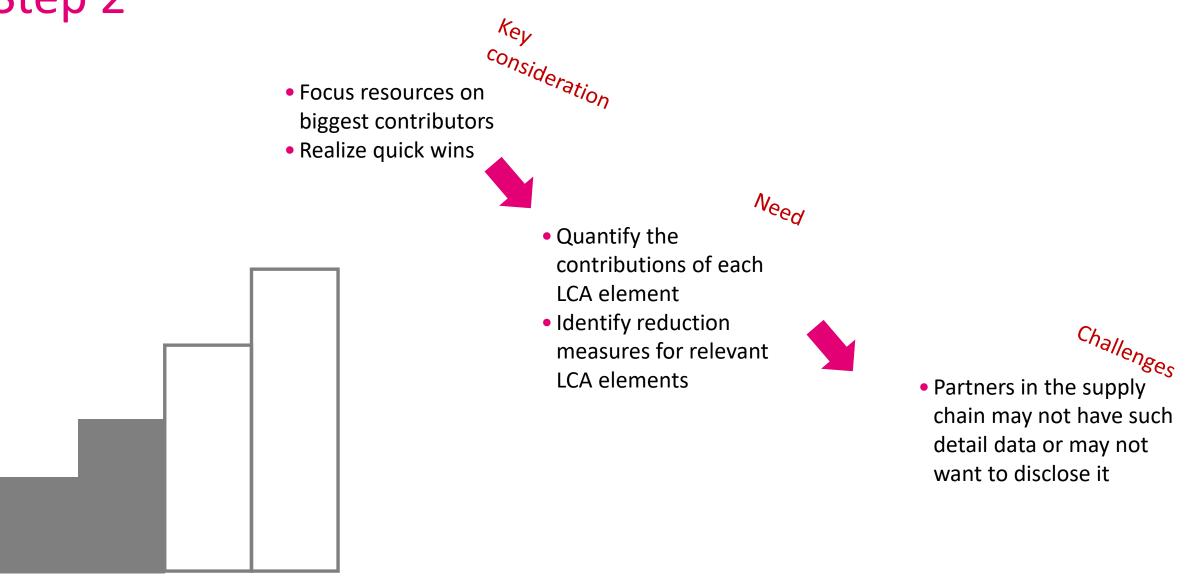




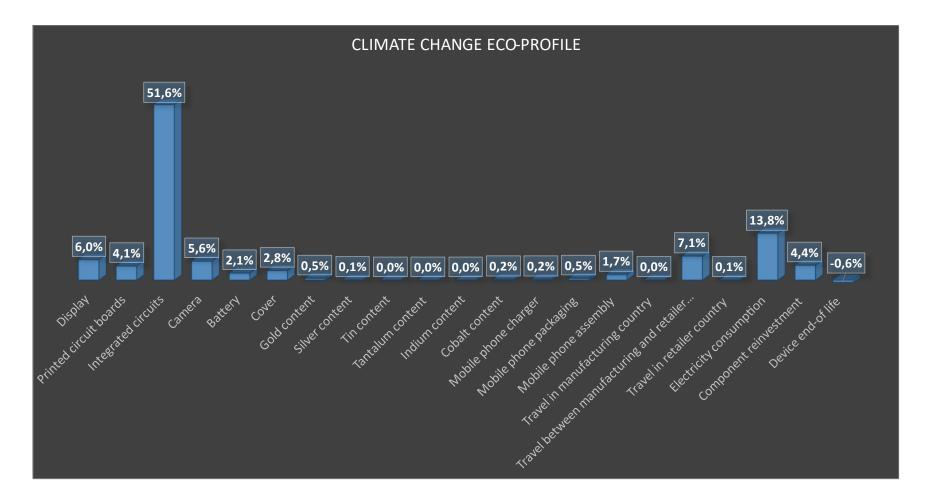
### THE ECO RATING METHODOLOGY Calculation Procedure







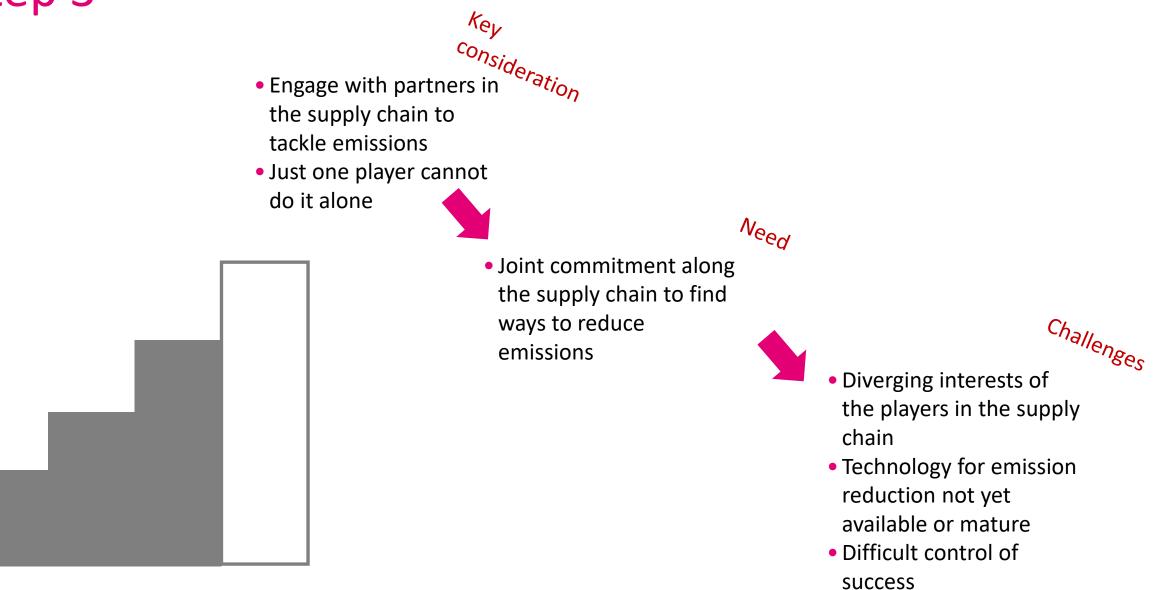
## Identifying the levers



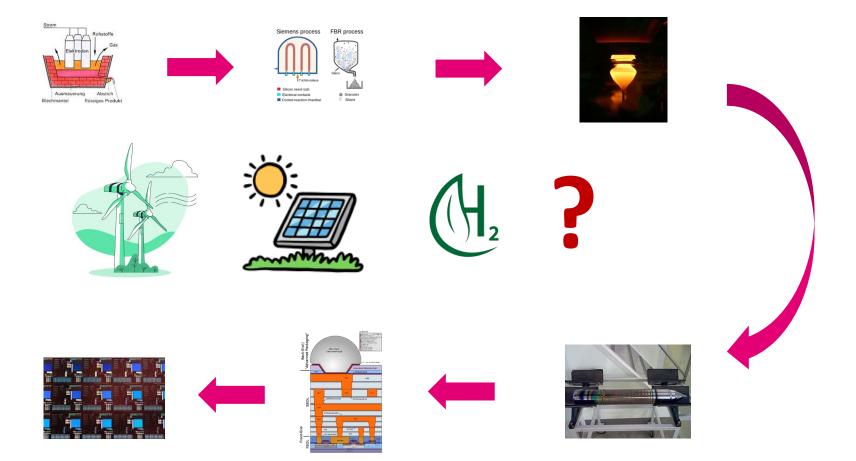
- Integrated circuits are the main contributor
- Resulting necessity to look into the manufacturing of integrated circuits to yield appreciable emission reductions for Smartphones

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Integrated circuits are the result of a wider supply chain; emission reduction contributions required from all players in the supply chain



## Semiconductors – very energy-intensive production



- Reductions in this area are essential for the emission reductions in the whole mobile phone industry
- Otherwise, pressure will increase on production volume reduction by longer use to still fulfill emission reduction targets
- Information exchange with the wider supply chain is meaningful to understand and/or trigger emission reduction concepts there

• Emission reductions need to be quantifiable and provable, also in view of the upcoming Green Claims directive

Key

 Residual emissions need to be compensated, so these need to be kept as small as possible



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Select reduction measures also in view of later measurability and provability

- How to deal with emission reductions that are not quantifiable?
- Emission reductions must exceed uncertainty range of original emission inventory

Thank You!

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